


- 1 Substrate: $1.59\text{mm} \pm 0.18\text{mm}$ [$0.0625" \pm 0.007"$] FR4/G10 or equivalent high temp material; Non-clad
- 2 Pins: material- Brass Alloy 360 1/2 hard; finish- $0.25\mu\text{m}$ [$10\mu"$] Au over $1.27\mu\text{m}$ [$50\mu"$] Ni (min.).
- 3 Solder Balls: Sn63Pb37

Description: Giga-snaP BGA SMT Foot

224 position terminal pins (0.8mm centers) to SMT solder balls (BGA type). Pin assignment 1:1.

Tolerances: diameters $\pm 0.03\text{mm}$ [$\pm 0.001"$], PCB perimeters $\pm 0.13\text{mm}$ [$\pm 0.005"$], PCB thicknesses $\pm 0.18\text{mm}$ [$\pm 0.007"$], pitches (from true position) $\pm 0.08\text{mm}$ [$\pm 0.003"$], all other tolerances $\pm 0.13\text{mm}$ [$\pm 0.005"$] unless stated otherwise. Materials and specifications are subject to change without notice.

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	<p>Drawing: A. Evans</p>	<p>Date: 5/27/09</p>	<p>File: SF-BGA224B-B-61 Dwg.mcd</p>	<p>Modified: 09/02/14</p>